

# Silicon Carbide (SiC) Diode – EliteSiC, TO247-3, 10 A, 1200 V SiC Merged PiN-Schottky (MPS) Dual Diode

# 123 321 T0247-3

TO247-3 CASE 340AK

# **UJ3D1210KSD**

#### **Description**

**onsemi** offers the 3<sup>rd</sup> generation of high performance SiC Merged-PiN-Schottky (MPS) diodes. With zero reverse recovery charge and 175 °C maximum junction temperature, these diodes are ideally suited for high frequency and high efficiency power systems with minimum cooling requirements.

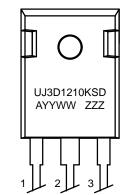
#### **Features**

- Maximum Operating Temperature of 175 °C
- Easy Paralleling
- Extremely Fast Switching not Dependent on Temperature
- No Reverse or Forward Recovery
- Enhanced Surge Current Capability, MPS Structure
- Excellent Thermal Performance, Ag Sintered
- 100% UIS Tested
- This Device is Pb-Free, Halogen Free and is ROHS Compliant

# **Typical Applications**

- Power Converters
- Industrial Motor Drives
- Switch Mode Power Supplies
- Power Factor Correction Modules

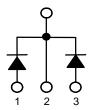
#### **MARKING DIAGRAM**



UJ3D1210KSD = Specific Device Code A = Assembly Location

YY = Year WW = Work Week ZZZ = Lot ID

#### **PIN CONNECTIONS**



#### **ORDERING INFORMATION**

See detailed ordering and shipping information on page 4 of this data sheet.

# **UJ3D1210KSD**

#### **MAXIMUM RATINGS**

Parameter	Symbol	Test Conditions	Value (Leg/Device)	Unit	
DC Blocking Voltage	$V_{R}$		1200	V	
Repetitive Peak Reverse Voltage, T <sub>J</sub> = 25 °C	$V_{RRM}$		1200	V	
Surge Peak Reverse Voltage	$V_{RSM}$		1200	V	
Maximum DC Forward Current	I <sub>F</sub>	T <sub>C</sub> = 160.7 °C	5/10	Α	
Non-repetitive Forward Surge Current Sine	I <sub>FSM</sub>	$T_C = 25  ^{\circ}\text{C},  t_p = 10  \text{ms}$	70/140	Α	
Halfwave		$T_C = 110 {}^{\circ}\text{C},  t_p = 10 \text{ms}$	63/126		
Repetitive Forward Surge Current Sine	I <sub>FRM</sub>	$T_C = 25  ^{\circ}\text{C},  t_p = 10  \text{ms}$	31.8/63.6	Α	
Halfwave, D = 0.1		$T_C = 110  ^{\circ}\text{C},  t_p = 10  \text{ms}$	18.6/37.2		
Non-repetitive Peak Forward Current	I <sub>F,max</sub>	$T_C = 25  ^{\circ}\text{C},  t_p = 10  \mu\text{s}$	525/1050	Α	
		$T_C = 110 {}^{\circ}\text{C},  t_p = 10 \mu\text{s}$	525/1050		
i <sup>2</sup> t Value	∫i <sup>2</sup> dt	$T_C = 25  ^{\circ}\text{C},  t_p = 10  \text{ms}$	24.5/98	A <sup>2</sup> s	
		$T_C = 110  ^{\circ}\text{C},  t_p = 10  \text{ms}$	19.5/78		
Power Dissipation	P <sub>tot</sub>	T <sub>C</sub> = 25 °C	136/272	W	
		T <sub>C</sub> = 160.7 °C	13/26		
Maximum Junction Temperature	$T_{J,max}$		175	°C	
Operating and Storage Temperature	T <sub>J</sub> , T <sub>STG</sub>		-55 to 175	°C	
Soldering Temperatures, Wavesoldering only Allowed at Leads	T <sub>sold</sub>	1.6 mm from case for 10 s	260	°C	

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

#### THERMAL CHARACTERISTICS

			Value (Leg/Device)		rice)	
Parameter	Symbol	Test Conditions	Min	Тур	Max	Unit
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$		-	0.85/0425	1.1/0.55	°C/W

## **ELECTRICAL CHARACTERISTICS** (T<sub>J</sub> = +25 °C unless otherwise specified)

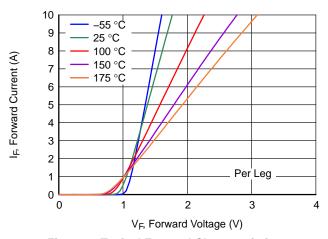
			Val	Value (Leg/Device)		
Parameter	Symbol	Test Conditions	Min	Тур	Max	Unit
Forward Voltage	V <sub>F</sub>	I <sub>F</sub> = 5 A/10 A, T <sub>J</sub> = 25 °C	-	1.4	1.6	V
		I <sub>F</sub> = 5 A/10 A, T <sub>J</sub> = 150 °C	-	1.85	2.3	1
		I <sub>F</sub> = 5 A/10 A, T <sub>J</sub> = 175 °C	-	2	2.6	1
Reverse Current	I <sub>R</sub>	V <sub>R</sub> = 1200 V, T <sub>J</sub> = 25 °C	-	5/10	55/110	μΑ
		V <sub>R</sub> = 1200 V, T <sub>J</sub> = 175 °C	-	160/320	-	1
Total Capacitive Charge (Note 1)	$Q_{C}$	V <sub>R</sub> = 800 V	-	27/54	-	nC
Total Capacitance	С	V <sub>R</sub> = 1 V, f = 1 MHz	-	250/500	-	pF
		V <sub>R</sub> = 400 V, f = 1 MHz	-	24.5/49	-	1
		V <sub>R</sub> = 800 V, f = 1 MHz	-	22/44	-	1
Capacitance Stored Energy	E <sub>C</sub>	V <sub>R</sub> = 800 V	-	8/16	-	μJ

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions. 1.  $Q_C$  is independent on  $T_J$ ,  $d_{IF}/dt$ , and  $I_F$  as shown in the application note <u>AND90316/D</u>

#### **UJ3D1210KSD**

#### **TYPICAL PERFORMANCE DIAGRAMS (PER LEG)**

I<sub>F</sub>, Forward Current (A)



**Figure 1. Typical Forward Characteristics** 

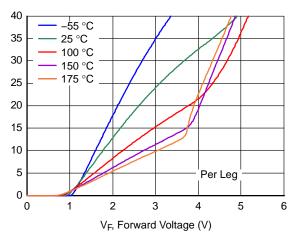


Figure 2. Typical Forward Characteristics in Surge Current

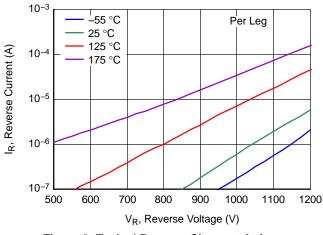


Figure 3. Typical Reverse Characteristics

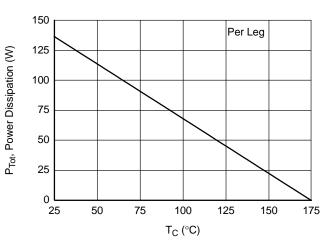


Figure 4. Power Dissipation

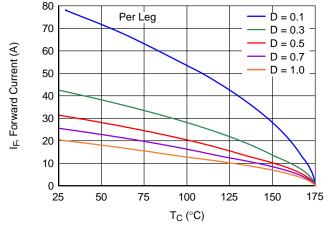


Figure 5. Diode Forward Current

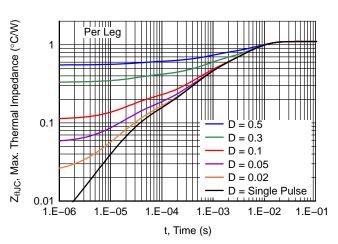


Figure 6. Maximum Transient Thermal Impedance

## **UJ3D1210KSD**

# TYPICAL PERFORMANCE DIAGRAMS (PER LEG) (CONTINUED)

 $Q_{C}\left( nC\right)$ 

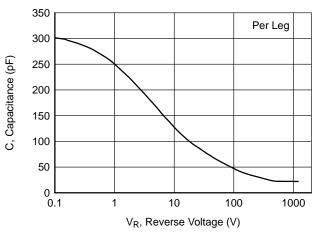


Figure 7. Capacitance vs. Reverse Voltage at 1 MHz

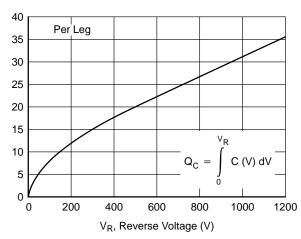


Figure 8. Typical Capacitive Charge vs. Reverse Voltage

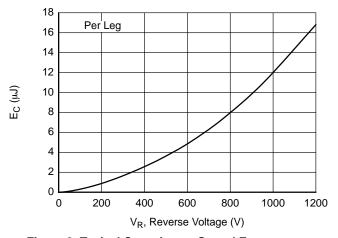


Figure 9. Typical Capacitance Stored Energy vs. Reverse Voltage

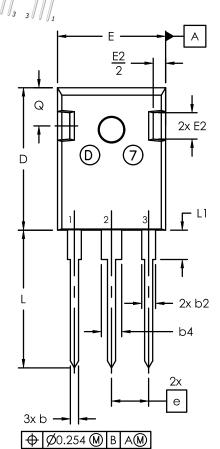
#### **ORDERING INFORMATION**

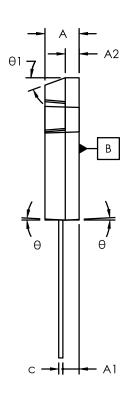
Part Number	Marking	Package	Shipping
UJ3D1210KSD	UJ3D1210KSD	TO247-3 (Pb-Free, Halogen Free)	600 / Tube

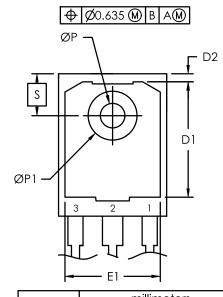




**DATE 14 APR 2025** 







SYM	millimeters				
317/1	MIN	MOM	MAX		
Α	4.70	5.03	5.31		
A1	2.21	2.40	2.59		
A2	1.50	2.03	2.49		
b	0.99	1.20	1.40		
b2	1.65	2.03	2.39		
b4	2.59	3.00	3.43		
c D	0.38	0.60	0.89		
	20.70	20.96	21.46		
D1	13.08	ı	ı		
D2	0.51	1.19	1.35		
Е	15.49	15.90	16.26		
е		5.44 BSC			
E1	13.00	13.30	13.60		
E2	3.43	3.89	5.20		
L	19.62	20.27	20.32		
L1	ı	ı	4.50		
ØP	3.40	3.60	3.80		
ØP1	7.06	7.19	7.39		
Q	5.38	5.62	6.20		
S		6.15 BSC			
θ	3°				
θ1	20°				
θ2		10°			

<b>→</b> <sub>Θ2</sub>
θ

#### NOTE:

- 1. Dimensioning and tolerancing as per ASME Y14.5 2018
- 2. Controlling dimension: millimeters
- 3. Package Outline in compliance with JEDEC standard var. AD.
- 4. Dimensions D & E does not include mold flash.
- 5. ØP to have max draft angle of 1.7° to the top with max. hole diameter of 3.91mm.

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DESCRIPTION:	TO247-3 15.90x20.96x5.03, 5.44P		PAGE 1 OF 1

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